

Product Compliance Declaration

Please see www.molex.com for the most up-to-date information.

Contact Information

Name Molex Product Compliance E-Mail Product.Compliance@molex.com

Part Information

Part Number 0348611116 Part Weight 3.53697G

Part Name HSAL2 ASSY 12 CKT RA HDR UNSLD KEY B

Product Composition

Name	Туре	CAS Number	Proportion (% Total)	Mass (Grams)
HSAL2 ASSY 12 CKT RA HDR UNSLD KEY B	Assembly		100	3.53697
HSAUTOLINKII HSG 12 CKT RA HDR KEY B	Component		46.0564	1.629
PS-ST GF30	Material		46.0564	1.629
PS-ST	Substance		27.0293	0.956019
GF-Fibre	Substance		13.7593	0.486664
Pigment portion, not to declare	Substance	system	0.5642	0.019955
Benzene, ethenyl-, polymer with 1,3-butadiene, hydrogenated	Substance	66070-58-4	3.1347	0.110875
Further Additives, not to declare	Substance	system	1.5688	0.055487
HSAL2 SOLDER NAIL PLATED	Component		4.8064	0.17
Cartridge Brass 70% Unplated	Material		4.5802	0.162
Copper	Substance	7440-50-8	3.2061	0.1134
Zinc (metal)	Substance	7440-66-6	1.3741	0.0486
Nickel Plating	Material		0.0905	0.0032

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Name	Туре	CAS Number	Proportion (% Total)	Mass (Grams)
Nickel	Substance	7440-02-0	0.0905	0.0032
Further Additives, not to declare	Substance	system	9E-06	3E-07
Tin Plating	Material		0.1357	0.0048
Tin	Substance	7440-31-5	0.1357	0.0048
HSALII 12CKT R/A CORE SOLD SEPARATELY	Assembly		49.1373	1.73797
HSAUTOLINKII LFH 6CKT FEM OVRMLD RA SHRT	Component		4.4635	0.157871
LCP-GF30	Material		1.6681	0.059
Carbon black	Substance	1333-86-4	0.0083	0.000295
LCP	Substance		1.1343	0.04012
Further Additives, not to declare	Substance	system	0.025	0.000885
GF-Fibre	Substance		0.5004	0.0177
HSAUTOLINKII LFH FEM 6CKT RA SHRT PLTD	Component		2.7954	0.098871
Tin Brass Unplated	Material		2.3749	0.084
Copper	Substance	7440-50-8	2.1018	0.07434
Tin	Substance	7440-31-5	0.0534	0.00189
Iron	Substance	7439-89-6	0.0006	0.000021
Lead	Substance	7439-92-1	0.0006	0.000021
Phosphorus	Substance	7723-14-0	0.0042	0.000147
Zinc (metal)	Substance	7440-66-6	0.2143	0.007581
Nickel Plating	Material		0.2036	0.0072
Nickel	Substance	7440-02-0	0.2035	0.007199
Further Additives, not to declare	Substance	system	2E-05	7E-07
Tin Plating	Material		0.2036	0.0072
Tin	Substance	7440-31-5	0.2036	0.0072
Gold Plating	Material		0.0133	0.000471
Cobalt	Substance	7440-48-4	3E-05	0.000001
Nickel	Substance	7440-02-0	3E-05	0.000001
Gold	Substance	7440-57-5	0.0132	0.000469
HSAUTOLINKII LFH 6CKT FEM OVRMLD RA LONG	Component		5.2304	0.184999
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Name	Туре	CAS Number	Proportion (% Total)	Mass (Grams)
LCP-GF30	Material		1.6681	0.059
Carbon black	Substance	1333-86-4	0.0083	0.000295
LCP	Substance		1.1343	0.04012
Further Additives, not to declare	Substance	system	0.025	0.000885
GF-Fibre	Substance		0.5004	0.0177
HSAUTOLINKII LFH FEM 6CKT RA LONG PLTD	Component		3.5624	0.125999
Phosphor Bronze 8%	Material		3.2231	0.114
Phosphor Bronze 8% Unplated	Material		3.1602	0.111775
Copper	Substance	7440-50-8	2.9014	0.10262
Tin	Substance	7440-31-5	0.2528	0.008942
Phosphorus	Substance	7723-14-0	0.006	0.000212
Tin Plating	Material		0.0629	0.002225
Tin	Substance	7440-31-5	0.0629	0.002225
Nickel Plating	Material		0.1645	0.005818
Nickel	Substance	7440-02-0	0.1645	0.005818
Further Additives, not to declare	Substance	system	2E-05	6E-07
Tin Plating	Material		0.1644	0.005813
Tin	Substance	7440-31-5	0.1644	0.005813
Gold Plating	Material		0.0104	0.000368
Cobalt	Substance	7440-48-4	3E-05	9E-07
Nickel	Substance	7440-02-0	3E-05	9E-07
Gold	Substance	7440-57-5	0.0103	0.000366
HSAUTOLINKII 12 CKT BISCUIT HOUSING	Component		4.6367	0.164
PS-ST GF30 Black	Material		4.6367	0.164
PS-ST	Substance		2.7097	0.095842
GF-Fibre	Substance		1.3992	0.049489
Pigment portion, not to declare	Substance	system	0.0308	0.001088
Further Additives, not to declare	Substance	system	0.1432	0.005064
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Name	Туре	CAS Number	Proportion (% Total)	Mass (Grams)
Benzene, ethenyl-, polymer with 1,3-butadiene, hydrogenated	Substance	66070-58-4	0.3539	0.012517
HSAUTOLINKII 12CKT RA INNER SHIELD PLTD	Component		23.7915	0.8415
Phosphor Bronze 8% Unplated	Material		22.9858	0.813
Copper	Substance	7440-50-8	21.1032	0.746415
Tin	Substance	7440-31-5	1.8389	0.06504
Phosphorus	Substance	7723-14-0	0.0437	0.001545
Nickel Plating	Material		0.5598	0.0198
Nickel	Substance	7440-02-0	0.5597	0.019798
Further Additives, not to declare	Substance	system	6E-05	0.000002
Tin Plating	Material		0.246	0.0087
Tin	Substance	7440-31-5	0.246	0.0087
HSAUTOLINKII 12CKT RA OUTER SHIELD PLTD	Component		11.0151	0.3896
Phosphor Bronze 8% Unplated	Material		9.8389	0.348
Copper	Substance	7440-50-8	9.0331	0.319499
Tin	Substance	7440-31-5	0.7871	0.02784
Phosphorus	Substance	7723-14-0	0.0187	0.000661
Nickel Plating	Material		0.6135	0.0217
Nickel	Substance	7440-02-0	0.6135	0.021698
Further Additives, not to declare	Substance	system	6E-05	0.000002
Tin Plating	Material		0.5626	0.0199
Tin	Substance	7440-31-5	0.5626	0.0199

ROHS Declaration Information

Regulatory Revision EU 2015/863

Compliance Status Compliant

Contained Substances Exceeding Threshold

None

Exemptions

None

REACH-SVHC Declaration Information

Regulatory Revision D(2020)9139-DC (19 Jan 2021)

Contained Substances Exceeding Threshold

None

GADSL Declaration Information

Regulatory Revision GADSL imported from IMDS

Contained Substances Exceeding Threshold

Substance Group	Substance Location	Threshold (PPM)	Concentration (PPM)	Intentionally Added
glass, oxide, chemicals	LCP-GF30	*Note	300,000	Yes
glass, oxide, chemicals	PS-ST GF30	*Note	320,000	Yes
glass, oxide, chemicals	PS-ST GF30 Black	*Note	320,000	Yes
copper	Phosphor Bronze, 8%	*Note	913,850	Yes
copper	Tin Brass	*Note	885,000	Yes
copper	Cartridge Brass 70% (CA260)	*Note	700,000	Yes
Cobalt	e-plate Au (Hardgold) (electrodeposited Hardgold	*Note	2,500	Yes
nickel powder [particle diameter < 1 mm]	Ep-Ni	*Note	997,500	Yes
nickel powder [particle diameter < 1 mm]	e-plate Au (Hardgold) (electrodeposited Hardgold	*Note	2,500	Yes

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Substance Group	Substance Location	Threshold (PPM)	Concentration (PPM)	Intentionally Added
lead	Phosphor Bronze, 8%	*Note	250	Yes
lead	Tin Brass	*Note	250	Yes
lead		*Note	500	Yes
lead	Cartridge Brass 70% (CA260)	*Note	350	Yes

^{*}Note: For GADSL substance declarable/prohibited threshold values, please reference http://www.gadsl.org/

Exemptions

Part Name	Exemption
Ep-Ni	33 Other application (Surface not routinely touched or nickel release rate < 0.5µg/cm2/week)
e-plate Au (Hardgold) (electrodeposited Hardgold Coatings)	34 Not applicable
Phosphor Bronze, 8%	44 Concentration within acceptable GADSL limits
Tin Brass	44 Concentration within acceptable GADSL limits
	44 Concentration within acceptable GADSL limits
Cartridge Brass 70% (CA260)	44 Concentration within acceptable GADSL limits

HFLH Declaration Information

Regulatory Revision IEC 61249-2-21

Contained Substances Exceeding Threshold

None

China ROHS Declaration Information

Part Number	0348611116							
Part Name	HSAL2 ASSY 12 CKT RA HDR UNSLD KEY B	(e)						
Part Information	on			Haz	zardous S	Substance	s	
Components			Lead	Mercury	Cadmium	Hex. Chromium	PBB	PBDE
HSAL2 ASSY	/ 12 CKT RA HDR UNSLD KEY B		0	0	0	0	0	0
HSAUTOLIN	KII HSG 12 CKT RA HDR KEY B		0	0	0	0	0	0

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Components	Lead	Mercury	Cadmium	Hex. Chromium	PBB	PBDE
HSAL2 SOLDER NAIL PLATED	0	0	0	0	0	0
HSALII 12CKT R/A CORE SOLD SEPARATELY	0	0	0	0	0	0
HSAUTOLINKII LFH 6CKT FEM OVRMLD RA SHRT	0	0	0	0	0	0
HSAUTOLINKII LFH FEM 6CKT RA SHRT PLTD	0	0	0	0	0	0
HSAUTOLINKII LFH 6CKT FEM OVRMLD RA LONG	0	0	0	0	0	0
HSAUTOLINKII LFH FEM 6CKT RA LONG PLTD	0	0	0	0	0	0
HSAUTOLINKII 12 CKT BISCUIT HOUSING	0	0	0	0	0	0
HSAUTOLINKII 12CKT RA INNER SHIELD PLTD	0	0	0	0	0	0
HSAUTOLINKII 12CKT RA OUTER SHIELD PLTD	0	0	0	0	0	0

Process Information

Component Plating / Surface Finish	N/A
Termination Base Alloy	N/A
Solder Alloy	N/A
Process Capability	N/A
Maximum Exposure Time (seconds)	N/A
Maximum Process Temperature (C)	N/A
Maximum Cycles at Reflow Temperature	N/A
J-STD-020 Moisture Sensitivity Level	N/A

Mar 24, 2021